



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Agarwal et al.

Application No. 09/590,795

Filed: June 8, 2000

Confirmation No. 9849

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING RUTHENIUM AND
TUNGSTEN CONTAINING LAYERS

Examiner: David Vu

Art Unit: 2818

Attorney Reference No. 6047-53173-01

MAIL STOP AMENDMENT
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CERTIFICATE OF MAILING

I hereby certify that this paper and the documents referred to as being attached or enclosed herewith are being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: MAIL STOP AMENDMENT COMMISSIONER FOR PATENTS, P.O. BOX 1450, ALEXANDRIA, VA 22313-1450 on the date shown below.

Attorney or Agent
for Applicant(s)

Date Mailed December 21, 2005

AMENDMENT AND REPLY TO RESTRICTION REQUIREMENT

This responds to the Office action dated September 22, 2005. Please amend the referenced application as follows:

Amendments to the Claims are reflected in the listing of claims, which begins on page 2.

Remarks begin on page 7.